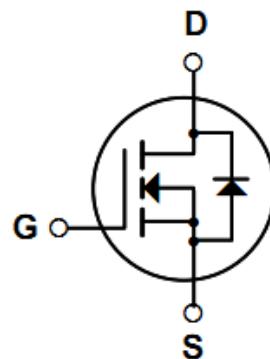
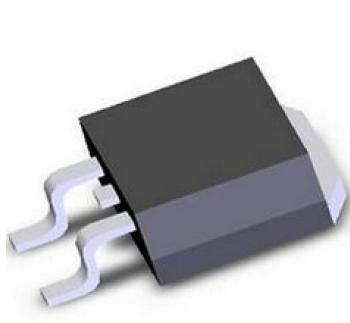


Description

This N-Channel MOSFET uses advanced trench technology and design to provide excellent $R_{DS(on)}$ with low gate charge. It can be used in a wide variety of applications.

Features

- 1) $V_{DS}=71V, I_D=90A, R_{DS(ON)}<6.8m\Omega @ V_{GS}=10V$
 - 2) Low gate charge.
 - 3) Green device available.
 - 4) Advanced high cell density trench technology for ultra $R_{DS(ON)}$.
 - 5) Excellent package for good heat dissipation.
-



Absolute Maximum Ratings $T_c=25^\circ C$, unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	71	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current ⁻¹	90	A
	Continuous Drain Current- $T_c=100^\circ C$	63	
	Pulsed Drain Current	320	A
P_D	Power Dissipation	170	W
E_{AS}	Single Pulse Avalanche Energy ⁵	550	mJ
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +175	°C

Thermal Characteristics

Symbol	Parameter	Ratings	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case ²	0.88	°C/W

Package Marking and Ordering Information

Part NO.	Marking	Package
RYN71A90T	N71A90T	TO-263

Electrical Characteristics $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250 \mu\text{A}$	71	74	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=500\text{V}$	---	---	1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 30\text{V}, V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
On Characteristics³						
$V_{\text{GS}(\text{th})}$	GATE-Source Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250 \mu\text{A}$	2	3	4	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On Resistance	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=40\text{A}$	---	5.9	6.8	$\text{m}\Omega$
Dynamic Characteristics⁴						
C_{iss}	Input Capacitance	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	---	4871	---	pF
C_{oss}	Output Capacitance		---	630.6	---	
C_{rss}	Reverse Transfer Capacitance		---	410.3	---	
Switching Characteristics⁴						
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DS}}=30\text{V}, I_{\text{D}}=42\text{A}, R_{\text{GEN}}=10 \Omega, V_{\text{GS}}=10\text{V}$	---	36.1	---	ns
t_r	Rise Time		---	54.3	---	ns
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	85.2	---	ns
t_f	Fall Time		---	37.3	---	ns
Q_g	Total Gate Charge	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=48\text{V}, I_{\text{D}}=84\text{A}$	---	85.7	---	nC
Q_{gs}	Gate-Source Charge		---	23.2	---	nC
Q_{gd}	Gate-Drain "Miller" Charge		---	31.2	---	nC
Drain-Source Diode Characteristics						
V_{SD}	Source-Drain Diode Forward Voltage ³	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=20\text{A}$	---	---	1.2	V
t_{rr}	Reverse Recovery Time	$I_{\text{F}}=84\text{A}$ $dI/dt=100\text{A}/\mu\text{s}$ ^(Note3)	---	88.3	---	ns
Q_{rr}	Reverse Recovery Charge		---	65.9	---	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leqslant 10$ sec.
3. Pulse Test: Pulse Width $\leqslant 300 \mu\text{s}$, Duty Cycle $\leqslant 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition: $T_j=25^\circ\text{C}, V_{\text{DD}}=35\text{V}, V_{\text{G}}=10\text{V}, L=0.5\text{mH}, R_g=25\Omega$

Typical Characteristics $T_J=25^\circ\text{C}$ unless otherwise noted

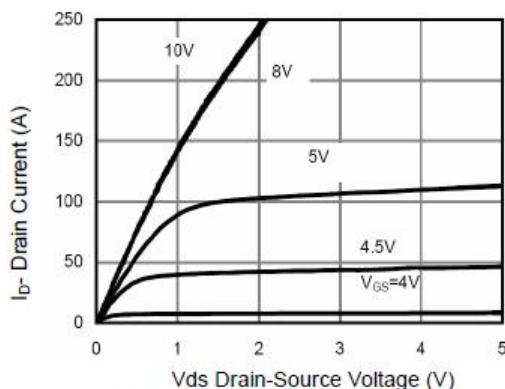


Figure 1 Output Characteristics

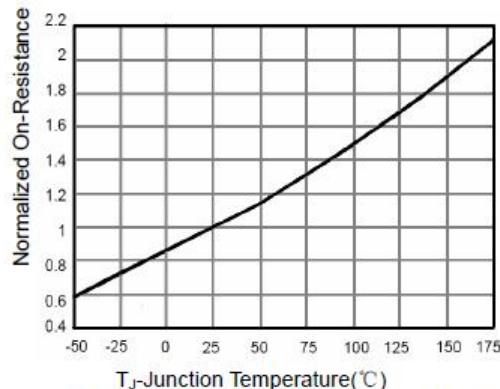


Figure 4 $R_{DS(on)}$ -JunctionTemperature

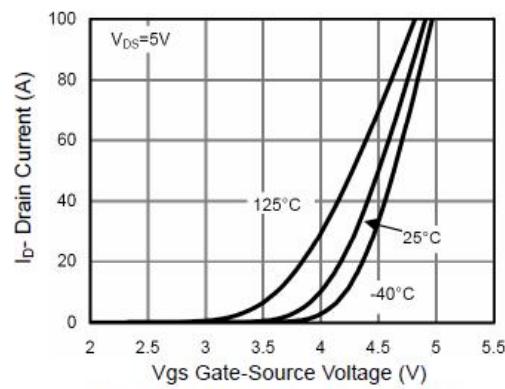


Figure 2 Transfer Characteristics

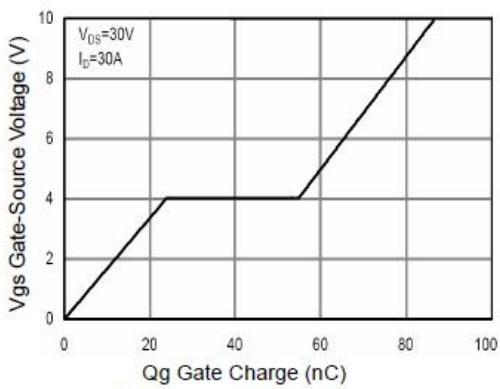


Figure 5 Gate Charge

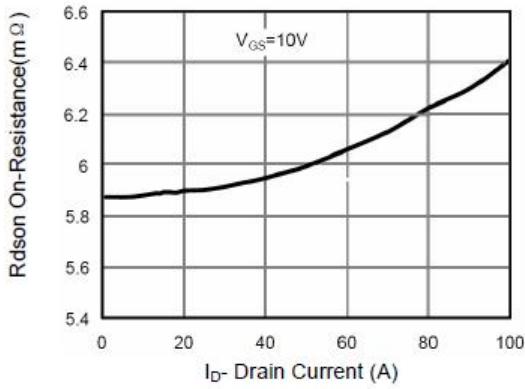


Figure 3 $R_{DS(on)}$ - Drain Current

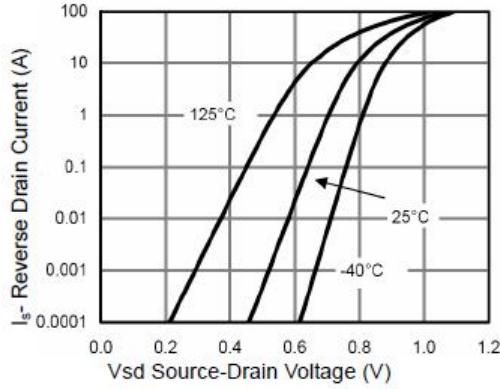
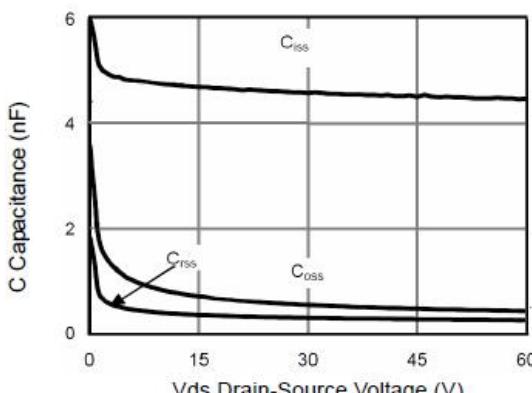
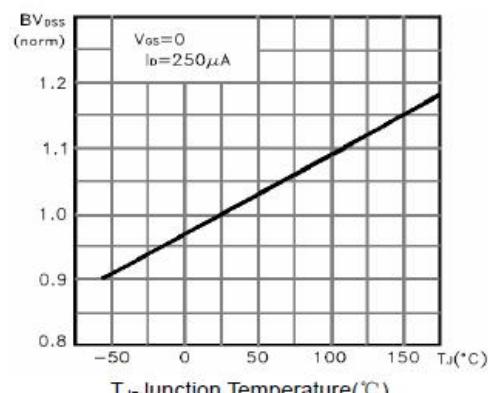
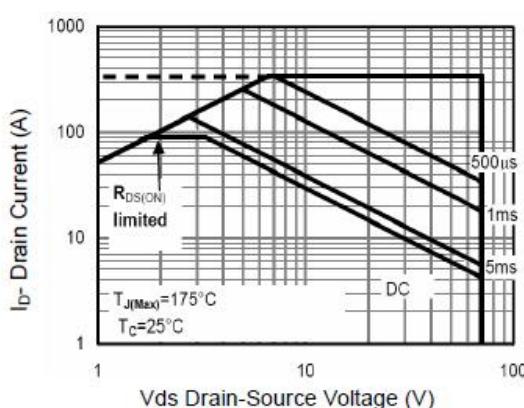
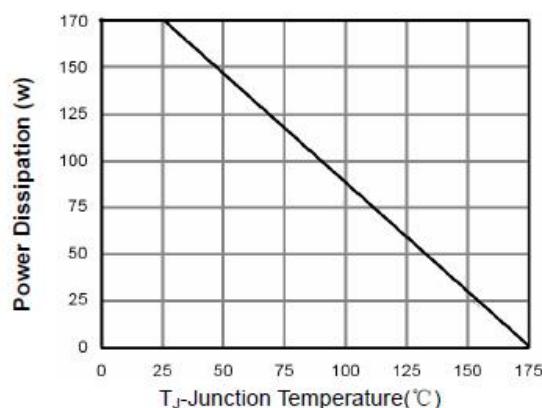
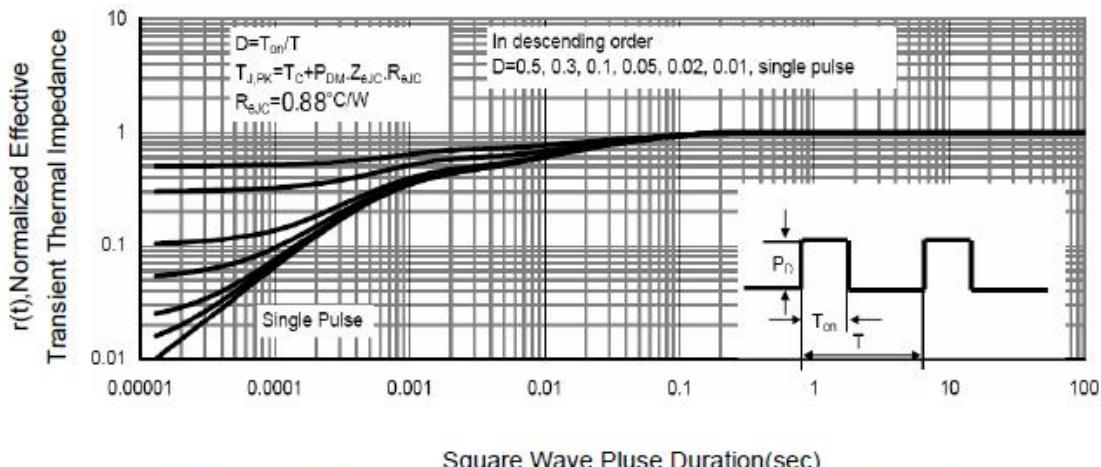


Figure 6 Source- Drain Diode Forward


Figure 7 Capacitance vs Vds

Figure 9 BV_{DSS} vs Junction Temperature

Figure 8 Safe Operation Area

Figure 10 Power De-rating

Figure 11 Normalized Maximum Transient Thermal Impedance